

SGSP216/P217
SGSP316/P317
SGSP516/P517

N-CHANNEL POWER MOS TRANSISTORS

HIGH SPEED SWITCHING APPLICATIONS

These products are diffused multi-cell silicon gate N-Channel enhancement mode Power-Mos field effect transistors.

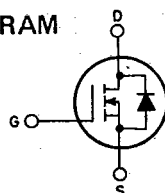
V_{DS}	$R_{DS(ON)}$	I_D
200V	0.75 Ω	6A
250V	1.2 Ω	6A

ABSOLUTE MAXIMUM RATINGS

	SOT-82 TO-220 TO-3	SGSP216 SGSP316 SGSP516	SGSP217 SGSP317 SGSP517
V_{DS}	Drain-source voltage ($V_{GS} = 0$)	250V	200V
V_{DGR}	Drain-gate voltage ($R_{GS} = 20 K\Omega$)	250V	200V
V_{GS}	Gate-source voltage	$\pm 20V$	
I_D	Drain current (continuous) $T_{case} = 25^\circ C$ at $T_{case} = 100^\circ C$	6A 3.8A	6A 3.8A
$I_{DM}(\bullet)$	Drain current (pulsed)	24A	24A
$I_{DLM}(\bullet)$	Drain inductive current, clamped	24A	24A
P_{tot}	Total dissipation at $T_{case} = 25^\circ C$ Derating factor	SOT-82 50W 0.4W/ $^\circ C$	TO-220 75W 0.6W/ $^\circ C$ TO-3 75W 0.6W/ $^\circ C$
T_{stg}	Storage temperature	-55 to 150 $^\circ C$	
T_j	Max. operating junction temperature	150 $^\circ C$	

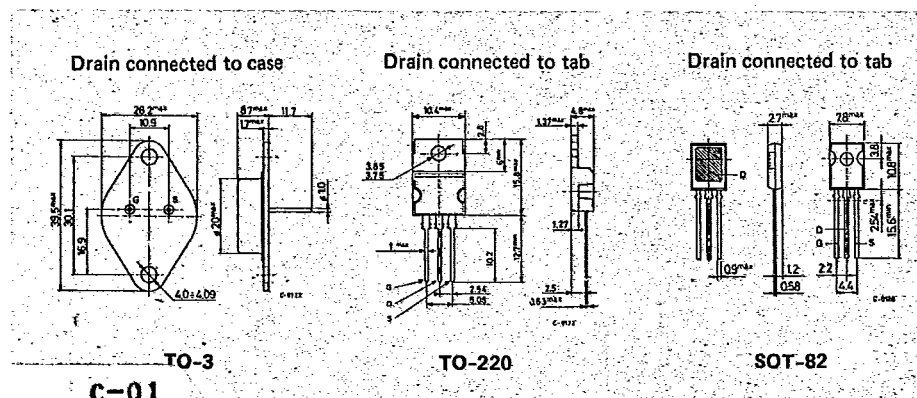
($\bullet$) Pulse width limited by safe operating area

INTERNAL SCHEMATIC DIAGRAM



MECHANICAL DATA

Dimensions in mm





SGSP216/P217
SGSP316/P317
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THERMAL DATA

		SOT-82	TO-220	TO-3
$R_{th j-case}$	Thermal resistance junction-case	max 2.5°C/W	1.6°C/W	1.6°C/W
T_L	Maximum lead temperature for soldering purpose	275	°C	

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Test conditions	Min.	Typ.	Max.	Unit
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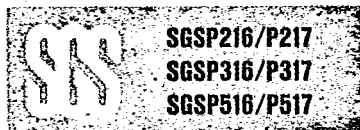
OFF

$V_{(BR) DSS}$	Drain-source breakdown voltage	$I_D = 250\mu\text{A}$ $V_{GS} = 0$ for SGSP216/P316/P516 for SGSP217/P317/P517	250 200		V V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max. Rating}$		250	μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 20\text{ V}$		100	nA

ON*

$V_{GS (th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ $I_D = 250\mu\text{A}$	2		4	V
$V_{DS (on)}$	Drain-source voltage	$V_{GS} = 10\text{ V}$ $I_D = 3\text{ A}$ for SGSP216/P316/P516 for SGSP217/P317/P517 $V_{GS} = 10\text{ V}$ $I_D = 6\text{ A}$ for SGSP216/P316/P516 for SGSP217/P317/P517 $V_{GS} = 10\text{ V}$ $I_D = 3\text{ A}$ $T_{case} = 100^\circ\text{C}$ for SGSP216/P316/P516 for SGSP217/P317/P517			3.60 2.25 8.10 5.00 7.20 4.50	V V V V V V
$R_{DS (on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}$ $I_D = 3\text{ A}$ for SGSP216/P316/P516 for SGSP217/P317/P517			1.20 0.75	Ω Ω
g_{fs}	Forward transconductance	$V_{DS} = 25\text{ V}$ $I_D = 3\text{ A}$	1.5			mho

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**ELECTRICAL CHARACTERISTICS** (continued)

Parameter	Test conditions	Min.	Typ.	Max.	Unit.
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DYNAMIC

C_{iss}	Input capacitance	$V_{DS} = 25 \text{ V}$ $f = 1 \text{ MHz}$ $V_{GS} = 0$	380	500	pF
C_{oss}	Output capacitance		100	130	pF
C_{rss}	Reverse transfer capacitance		50	65	pF

SWITCHING

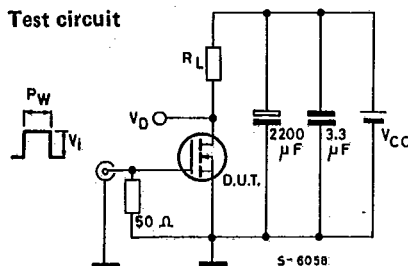
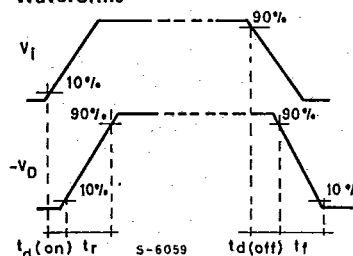
$t_d(\text{on})$	Turn-on time	$V_{CC} = 100 \text{ V}$ $I_D = 2.5 \text{ A}$ $V_i = 10 \text{ V}$ $R_i = 50 \Omega$ (see test circuit)	27		ns
t_r	Rise time		27		ns
$t_d(\text{off})$	Turn-off delay time		30		ns
t_f	Fall time		30		ns

SOURCE DRAIN DIODE

I_{SD}	Source drain current			6	A
$I_{SDM}(\bullet)$	Source drain current (pulsed)			24	A
V_{SD}	Forward on voltage	$I_{SD} = 6 \text{ A}$ $V_{GS} = 0$		1.3	V
t_{on}	Turn-on time	$I_{SD} = 6 \text{ A}$ $V_{GS} = 0$ $di/dt = 100 \text{ A}/\mu\text{s}$	100		ns
t_{rr}	Reverse recovery time		180		ns

* Pulsed: pulse duration $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$

(\bullet) Pulse width limited by safe operating area.

SWITCHING TIMES RESISTIVE LOAD**Test circuit**Pulse width $\leq 100 \mu\text{s}$ Duty cycle $\leq 2\%$ $V_i = 10 \text{ V}$ **Waveforms**



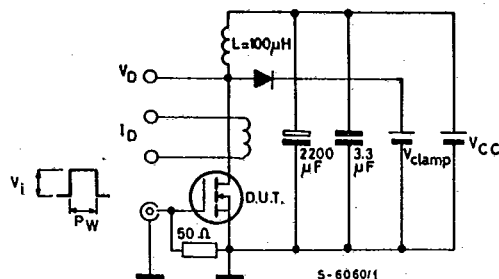
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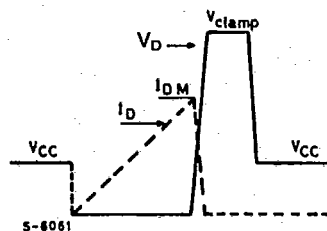
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CLAMPED INDUCTIVE LOAD

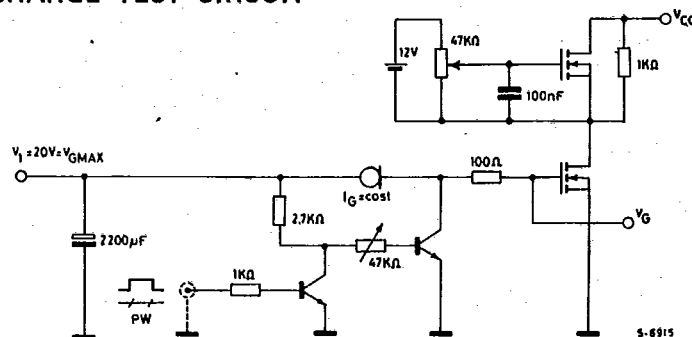
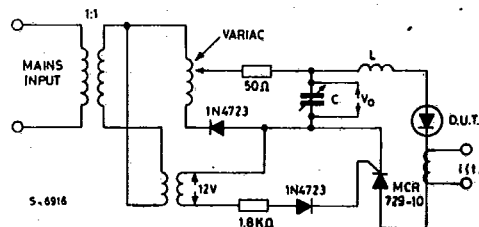
Test circuit



Waveforms

 $V_i = 12V$ Pulse width: adjusted to obtain specified I_{DM} . $V_{clamp} = 0.75 V_{(BR)}$ DSS

GATE CHARGE TEST CIRCUIT

PW adjusted to obtain required V_G DIODE BODY-DRAIN t_{rr} MEASUREMENT

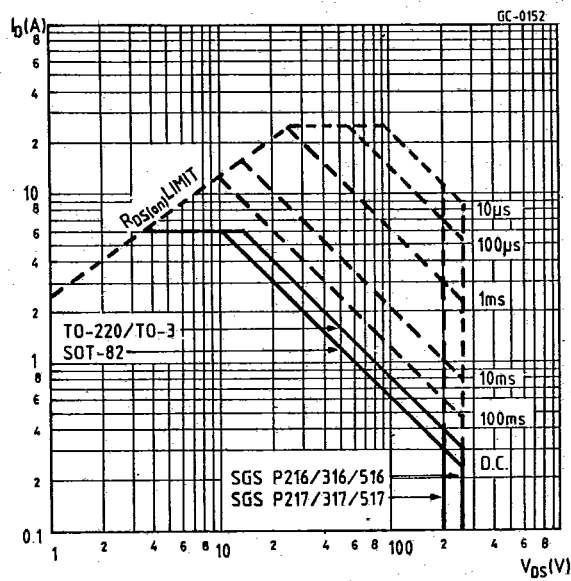
Jedec test circuit

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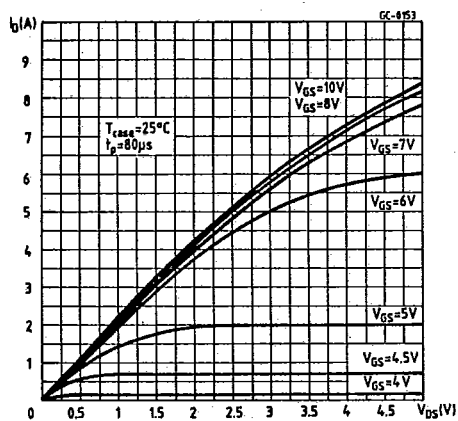
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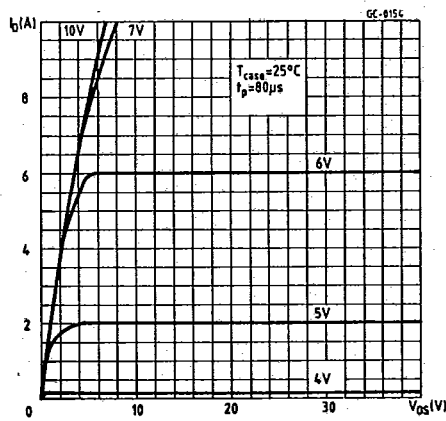
Safe operating areas



Output characteristics



Output characteristics



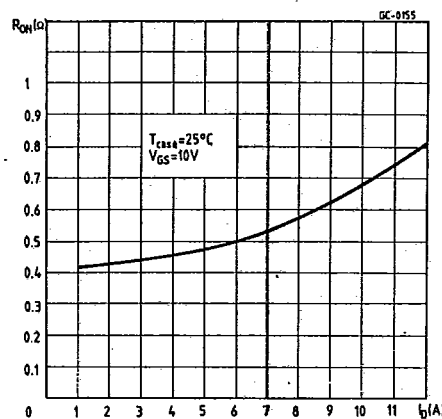


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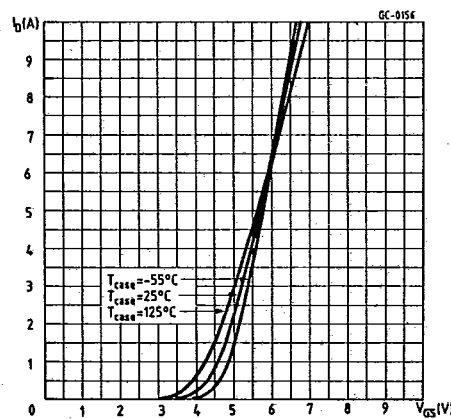
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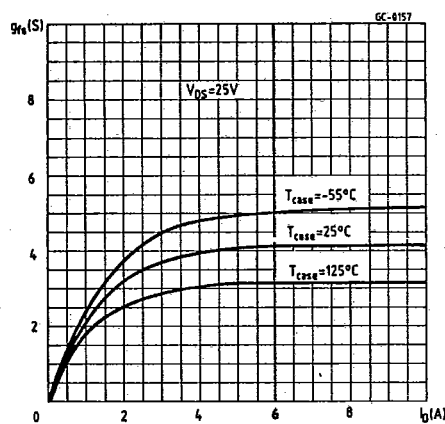
Static drain-source on resistance



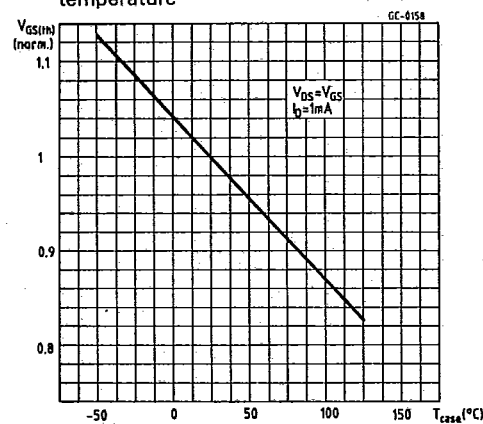
Transfer characteristics



Transconductance



Normalized gate threshold vs. temperature



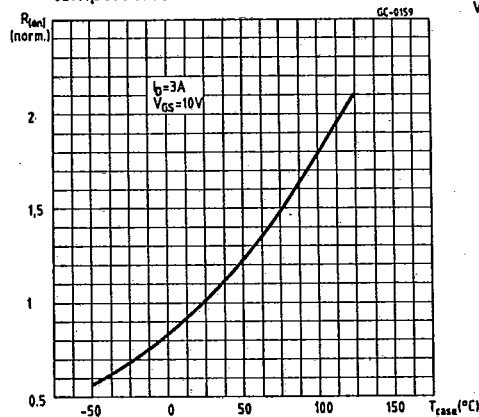


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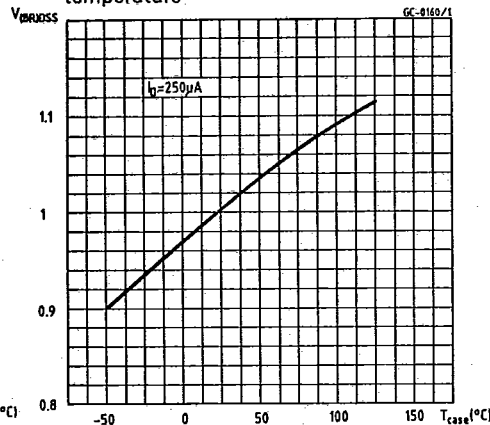
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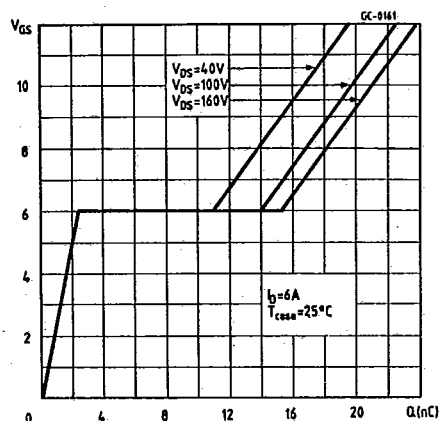
Normalized on resistance vs temperature



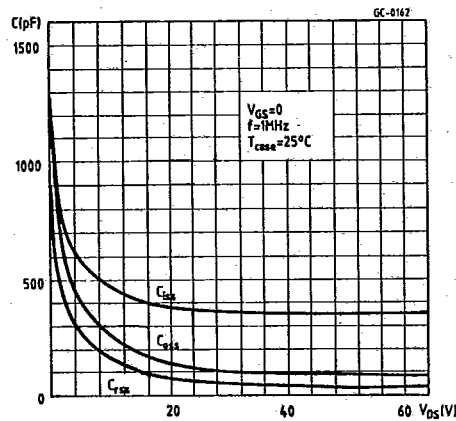
Normalized breakdown voltage vs temperature



Gate charge vs. gate to source voltage



Capacitance variation

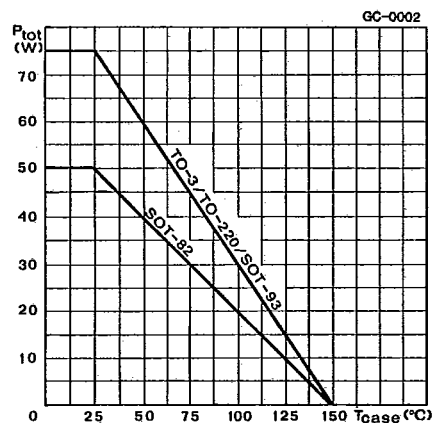


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Derating curve



Source-drain diode forward characteristics

